SNOSBR7D - MAY 2000 - REVISED APRIL 2013

# LM78XX Series Voltage Regulators

Check for Samples: LM7805C, LM7812C, LM7815C

#### **FEATURES**

- Output Current in Excess of 1A
- Internal Thermal Overload Protection
- No External Components Required
- Output Transistor Safe Area Protection
- Internal Short Circuit Current Limit
- Available in the Aluminum TO-3 Package

#### DESCRIPTION

The LM78XX series of three terminal regulators is available with several fixed output voltages making them useful in a wide range of applications. One of these is local on card regulation, eliminating the distribution problems associated with single point regulation. The voltages available allow these regulators to be used in logic systems, instrumentation, HiFi, and other solid state electronic equipment. Although designed primarily as fixed voltage regulators these devices can be used with external components to obtain adjustable voltages and currents.

The LM78XX series is available in an aluminum TO-3 package which will allow over 1.0A load current if adequate heat sinking is provided. Current limiting is included to limit the peak output current to a safe value. Safe area protection for the output transistor is provided to limit internal power dissipation. If internal power dissipation becomes too high for the heat sinking provided, the thermal shutdown circuit takes over preventing the IC from overheating.

Considerable effort was expanded to make the LM78XX series of regulators easy to use and minimize the number of external components. It is not necessary to bypass the output, although this does improve transient response. Input bypassing is needed only if the regulator is located far from the filter capacitor of the power supply.

For output voltage other than 5V, 12V and 15V the LM117 series provides an output voltage range from 1.2V to 57V.

### **VOLTAGE RANGE**

LM7805C: 5VLM7812C: 12VLM7815C: 15V

#### **Connection Diagrams**

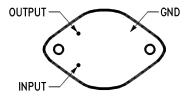


Figure 1. Metal Can Package TO-3 Aluminum Bottom View

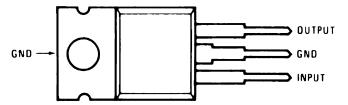
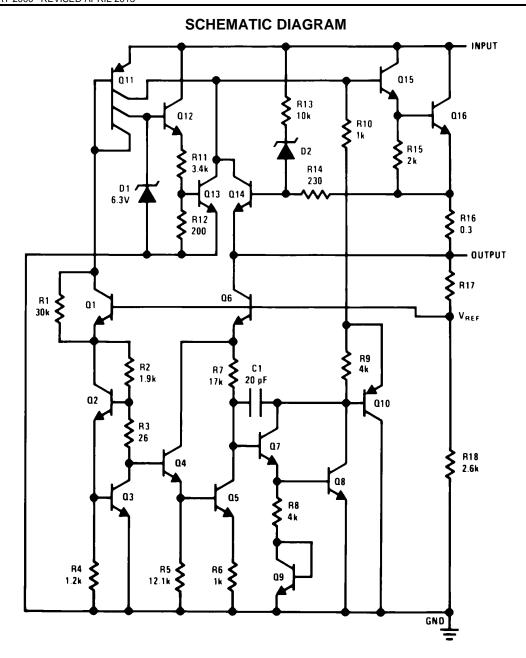


Figure 2. Plastic Package TO-220 (NDE) Top View See Package Number NDE0003B

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Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.









These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

## **ABSOLUTE MAXIMUM RATINGS**(1)(2)

Input Voltage (V <sub>O</sub> = 5V, 12V and 15V)	35V				
Internal Power Dissipation (3)	Internal Power Dissipation <sup>(3)</sup>				
Operating Temperature Range (T <sub>A</sub> )	0°C to +70°C				
Maximum lunction Townserture	(TO-3 Package)	150°C			
Maximum Junction Temperature	(NDE Package)	150°C			
Storage Temperature Range		−65°C to +150°C			
Lond Townson (Coldonia a 40 occ)	TO-3 Package	300°C			
Lead Temperature (Soldering, 10 sec.)	TO-220 Package NDE	230°C			

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. For ensured specifications and the test conditions, see Electrical Characteristics.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.
- (3) Thermal resistance of the TO-3 package is typically 4°C/W junction to case and 35°C/W case to ambient. Thermal resistance of the TO-220 package (NDE) is typically 4°C/W junction to case and 50°C/W case to ambient.

#### **ELECTRICAL CHARACTERISTICS LM78XXC**(1)

 $0^{\circ}C \le T_{J} \le 125^{\circ}C$  unless otherwise noted.

		5V			12V								
	Input Voltage (u	nless otherw	ise noted)		10V		19V				Units		
Symbol	Parameter		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max		
Vo	Output Voltage $Tj = 25^{\circ}C$ , 5 mA $\leq I_O \leq 1A$		4.8	5	5.2	11.5	12	12.5	14.4	15	15.6	٧	
		$P_D \le 15W$ , 5 mA $\le I_O \le 1A$				5.25	11.4		12.6	14.2	•	15.7	٧
									5		5		
	$V_{MIN} \le V_{IN} \le V_{MAX}$		$(7.5 \le V_{IN} \le 20)$			$(14.5 \le V_{IN} \le 27)$			(17.5	V			
$\Delta V_{O}$	Line Regulation	$I_0 = 500$	Tj = 25°C		3	50	4 120				4	150	mV
		mA	$\Delta V_{IN}$	$(7 \le V_{IN} \le 25)$			$14.5 \le V_{IN} \le 30$		≤ 30)	(17.5	$5 \le V_{IN}$	≤ 30)	V
			0°C ≤ Tj ≤ +125°C			50	120					150	mV
			$\Delta V_{IN}$	(8 ≤ V <sub>IN</sub> ≤ 20)			$(15 \le V_{IN} \le 27)$			$(18.5 \le V_{IN} \le 30)$			V
		I <sub>O</sub> ≤ 1A	Tj = 25°C	50			120				mV		
			$\Delta V_{IN}$	$(7.5 \le V_{IN} \le 20)$			$(14.6 \le V_{IN} \le 27)$			$(17.7 \le V_{IN} \le 30)$			V
			0°C ≤ Tj ≤ +125°C			25			60			75	mV
		$\Delta V_{IN}$		$\Delta V_{IN}$ $(8 \le V_{IN} \le 12)$			(16	$(16 \le V_{IN} \le 22)$			$(20 \le V_{IN} \le 26)$		
$\Delta V_{O}$	Load Regulation	Tj = 25°C	5 mA ≤ I <sub>O</sub> ≤ 1.5A		10	50		12	120		12	150	mV
			250 mA ≤ I <sub>O</sub> ≤ 750 mA			25			60			75	mV
		5 mA ≤ I <sub>O</sub> ≤ +125°C	1A, 0°C ≤ Tj ≤			50			120		150		mV
IQ	Quiescent Current	I <sub>O</sub> ≤ 1A	Tj = 25°C			8			8			8	mA
			0°C ≤ Tj ≤ +125°C			8.5			8.5			8.5	mA
$\Delta I_Q$	Quiescent Current	5 mA ≤ I <sub>O</sub> ≤			0.5			0.5			0.5	mA	
	Change	Tj = 25°C, I	<sub>O</sub> ≤ 1A		1.0		1.0			1.0			mA
		V <sub>MIN</sub> ≤ V <sub>IN</sub> ≤	$V_{MIN} \le V_{IN} \le V_{MAX}$			≤ 20)	(14.8	8 ≤ V <sub>IN</sub> :	≤ 27)	(17.9	$0 \le V_{IN}$	≤ 30)	V
		I <sub>O</sub> ≤ 500 m/	A, 0°C ≤ Tj ≤ +125°C			1.0						1.0	mA
		V <sub>MIN</sub> ≤ V <sub>IN</sub> ≤	≤ V <sub>MAX</sub>	(7 :	≤ V <sub>IN</sub> ≤	25)				(17.5	V		

<sup>(1)</sup> All characteristics are measured with capacitor across the input of 0.22 μF, and a capacitor across the output of 0.1μF. All characteristics except noise voltage and ripple rejection ratio are measured using pulse techniques (t<sub>w</sub> ≤ 10 ms, duty cycle ≤ 5%). Output voltage changes due to changes in internal temperature must be taken into account separately.



## **ELECTRICAL CHARACTERISTICS LM78XXC**<sup>(1)</sup> (continued)

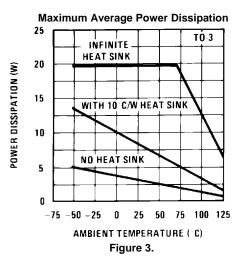
 $0^{\circ}\text{C} \le \text{T}_{\text{J}} \le 125^{\circ}\text{C}$  unless otherwise noted.

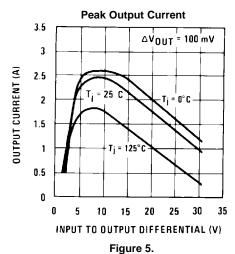
	Outpo		5V			12V						
	Input Voltage (un	less otherwise noted)		10V		19V			23V			Units
Symbol	Parameter	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
V <sub>N</sub>	Output Noise Voltage	$T_A = 25^{\circ}C$ , 10 Hz $\leq f \leq$ 100 kHz		40			75			90		μV
	Ripple Rejection	f = 120 Hz I <sub>O</sub> ≤ 1A, Tj = 25°C or	62	80		55	72		54	70		dB
$\Delta V_{IN}/\Delta$		I <sub>O</sub> ≤ 500 mA	62			55			54			dB
V <sub>OUT</sub>		0°C ≤ Tj ≤ +125°C										
		$V_{MIN} \le V_{IN} \le V_{MAX}$	(8 ≤ V <sub>IN</sub> ≤ 18)			$(15 \le V_{IN} \le 25)$			$(18.5 \le V_{IN} \le 28.5)$			V
R <sub>O</sub>	Dropout Voltage	Tj = 25°C, I <sub>OUT</sub> = 1A		2.0			2.0			2.0		V
	Output Resistance	f = 1 kHz		8			18			19		mΩ
	Short-Circuit Current Tj = 25°C			2.1			1.5			1.2		Α
Peak Output Current   Tj = 25°C			2.4			2.4			2.4		Α	
	Average TC of V <sub>OUT</sub>	0°C ≤ Tj ≤ +125°C, I <sub>O</sub> = 5 mA		0.6			1.5			1.8		mV/°C
V <sub>IN</sub>	Input Voltage											
	Required to $Tj = 25$ °C, $I_O \le 1$ A Maintain			7.5		14.6			17.7			V
	Line Regulation											

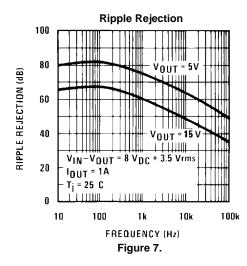
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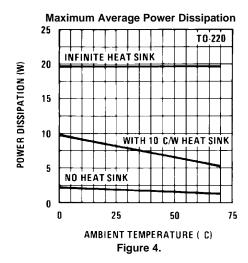


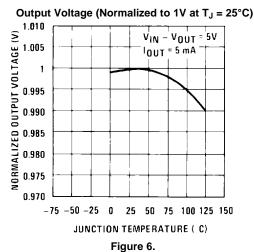
#### TYPICAL PERFORMANCE CHARACTERISTICS

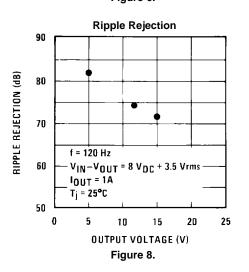






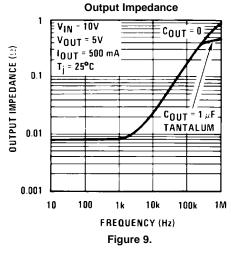


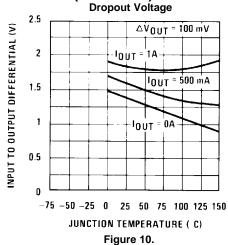


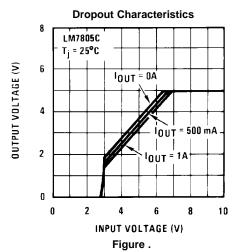


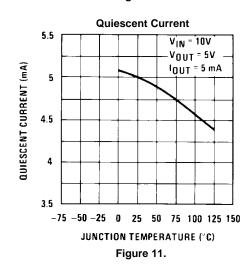


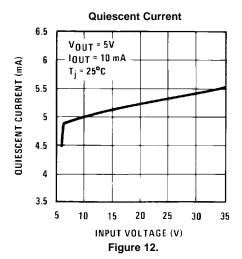
## TYPICAL PERFORMANCE CHARACTERISTICS (continued)













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## **REVISION HISTORY**

C	hanges from Revision C (April 2013) to Revision D	Pag	е
•	Changed layout of National Data Sheet to TI format		6





26-Jul-2016

#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
LM7805CT	ACTIVE	TO-220	NDE	3	45	TBD	Call TI	Call TI	0 to 70	LM340T5 7805 P+	Samples
LM7805CT/NOPB	ACTIVE	TO-220	NDE	3	45	Pb-Free (RoHS Exempt)	CU SN	Level-1-NA-UNLIM	0 to 70	LM340T5 7805 P+	Samples
LM7805MP/NOPB	ACTIVE	SOT-223	DCY	4	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	N00A	Samples
LM7805MPX/NOPB	ACTIVE	SOT-223	DCY	4	2000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 125	N00A	Samples
LM7805S/NOPB	ACTIVE	DDPAK/ TO-263	KTT	3	45	Pb-Free (RoHS Exempt)	CU SN	Level-3-245C-168 HR	0 to 125	LM340S -5.0 P+	Samples
LM7805SX/NOPB	ACTIVE	DDPAK/ TO-263	KTT	3	500	Pb-Free (RoHS Exempt)	CU SN	Level-3-245C-168 HR	0 to 125	LM340S -5.0 P+	Samples
LM7815CT/NOPB	ACTIVE	TO-220	NDE	3	45	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	0 to 70	LM340T15 7815 P+	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



## PACKAGE OPTION ADDENDUM

26-Jul-2016

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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## DCY (R-PDSO-G4)

#### PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters (inches).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion.

D. Falls within JEDEC TO-261 Variation AA.

# KTT (R-PSFM-G3)

# PLASTIC FLANGE-MOUNT PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- 3. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash or protrusion not to exceed 0.005 (0,13) per side.
- ⚠ Falls within JEDEC T0—263 variation AA, except minimum lead thickness and minimum exposed pad length.



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